

Amendments to the Claims:

Listing of Claims:

1-241. (canceled)

5 242. (previously presented) A chip packaging method comprising:
 joining a die and a substrate;
 after said joining said die and said substrate, depositing a passive device over said
substrate, wherein said passive device has a portion not over said die; and
 separating said substrate.

10

243. (previously presented) A chip packaging method comprising:
 joining a die and a substrate;
 after said joining said die and said substrate, depositing a passive device having a
first connection point connected to said die;
15 after said depositing said passive device, depositing a metal bump connected to a
second connection point of said passive device; and
 separating said substrate.

244. (currently amended) A chip packaging method comprising:
20 providing a first die having a first top surface at a horizontal level;
 providing a second die having a second top surface at said horizontal level;
 depositing a passive device over said horizontal level, wherein said passive device
has a portion not over said first and second dies; and
 depositing a metal trace over said horizontal level, wherein said metal trace extends
25 across an edge of said first or second die. ~~has a portion not over said first and second~~
~~dies.~~

245. (previously presented) The method of claim 242, wherein said substrate comprises metal.

246. (currently amended) The method of claim 242 further comprising joining a film and
5 said substrate, ~~followed by said joining said die and said substrate,~~ an opening in said film exposing said substrate, followed by said joining said die and said substrate exposed by
said opening.

247. (previously presented) The method of claim 246, wherein forming said opening in
10 said film comprising punching.

248. (previously presented) The method of claim 246, wherein said film comprises metal.

249. (currently amended) The method of claim 242, after said joining said die and said
15 substrate, further comprising depositing a patterned circuit layer over said die and over
 said substrate, said patterned circuit layer extending across an edge of said die, followed
 by said separating said substrate, ~~wherein said patterned circuit layer extends to a place-~~
~~not over said die.~~

20 250. (previously presented) The method of claim 249, wherein said depositing said
 patterned circuit layer comprises electroplating.

25 251. (previously presented) The method of claim 249, wherein said depositing said
 patterned circuit layer comprises sputtering.

252. (previously presented) The method of claim 242, wherein said depositing said
 passive device comprises electroplating.

253. (withdrawn) The method of claim 242, wherein said depositing said passive device comprises sputtering.

254. (previously presented) The method of claim 242, after said joining said die and said substrate, further comprising depositing a solder bump over said substrate, followed by said separating said substrate.
5

255. (withdrawn) The method of claim 242, after said joining said die and said substrate, further comprising depositing a gold bump over said substrate, followed by said separating said substrate.
10

256. (previously presented) The method of claim 242, wherein said depositing said passive device is followed by said separating said substrate.

15 257. (previously presented) The method of claim 243, wherein said substrate comprises metal.

258. (currently amended) The method of claim 243 further comprising joining a film and said substrate, ~~followed by said joining said die and said substrate,~~ an opening in said film exposing said substrate, followed by said joining said die and said substrate exposed by said opening.
20

259. (previously presented) The method of claim 258, wherein forming said opening in said film comprising punching.

25
260. (previously presented) The method of claim 258, wherein said film comprises metal.

261. (currently amended) The method of claim 243, after said joining said die and said substrate, further comprising depositing a patterned circuit layer over said die and over said substrate, said patterned circuit layer extending across an edge of said die, followed by said separating said substrate, ~~wherein said patterned circuit layer extends to a place not over said die.~~

5

262. (previously presented) The method of claim 261, wherein said depositing said patterned circuit layer comprises electroplating.

10 263. (previously presented) The method of claim 261, wherein said depositing said patterned circuit layer comprises sputtering.

264. (previously presented) The method of claim 243, wherein said depositing said passive device comprises electroplating.

15 265. (withdrawn) The method of claim 243, wherein said depositing said passive device comprises sputtering.

266. (previously presented) The method of claim 243, wherein said depositing said metal bump comprises depositing a solder bump connected to said second connection point.

20

267. (withdrawn) The method of claim 243, wherein said depositing said metal bump comprises depositing a gold bump connected to said second connection point.

25 268. (previously presented) The method of claim 243, wherein said depositing said metal bump is followed by said separating said substrate.

269. (previously presented) The method of claim 244, wherein said depositing said metal trace comprises electroplating.

270. (previously presented) The method of claim 244, wherein said depositing said metal trace comprises sputtering.
5

271. (previously presented) The method of claim 244, wherein said depositing said passive device comprises electroplating.

10 272. (withdrawn) The method of claim 244, wherein said depositing said passive device comprises sputtering.

273. (previously presented) The method of claim 244, after said depositing said passive device and said depositing said metal trace, further comprising depositing a solder bump over said horizontal level.
15

274. (withdrawn) The method of claim 244, after said depositing said passive device and said depositing said metal trace, further comprising depositing a gold bump over said horizontal level.

20